



C Series Low ESL Flip Type

Type: C0510 [EIA CC0204]

C0816 [EIA CC0306] C1220 [EIA CC0508] C1632 [EIA CC0612]

Issue date: April 2011

TDK MLCC US Catalog



REMINDERS

Please read before using this product

SAFETY REMINDERS



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C Series

Low ESL Flip Type

Type: C0510, C0816, C1220, C1632

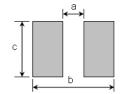
Features



- Positioning the electrodes along the length of the chip device, reduces ESR and ESL components over conventional products.
- Provides high frequency noise suppression effect because the resonating frequency is high.
- Flipped geometry provides low inductance (less than 400 pH).
- Provides stabilization of power line voltage.
- · Suitable for IC decoupling application.

PC Board Pattern





Case	Dimensions (mm)					
Size	Size a b		С			
C0510	0.2	0.6	1.0			
C0816	0.3	1.0	1.6			
C1220	0.5	1.6	2.0			
C1632	0.75	2.2	3.2			

1632

Applications



· Bias line in CPU

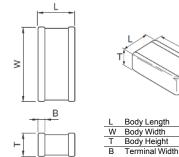
· Decoupling CPU power line

High speed digital IC/decouplingPC, cell phones, camcorders, etc.

Shape & Dimensions



X5R OJ 106 M T XXXX



Dimensions in mm



Series Name ——

Case Code	Length	Width
C0510	0.52 ± 0.05	1.00 ± 0.05
C0816 (C<1µF)	0.80 ± 0.10	1.60 ± 0.10
C0816 (C≥1µF)	0.80 ± 0.15	1.60 ± 0.20
C1220	1.25 ± 0.20	2.00 ± 0.20
C1608	1.60 ± 0.20	3.20 ± 0.20

Temperature Characteristic

Temperature Characteristics	Capacitance Change	Temperature Range
X5R	± 15%	-55 to +85°C
X6S	± 22%	-55 to +105°C
X7R	± 15%	-55 to +125°C
X7S	± 22%	-55 to +125°C

Rated Voltage (DC)

Voltage Code	Voltage (DC)
0G	4V
0J	6.3V
1A	10V
1C	16V
1E	25V
1H	50V

Internal Codes

Packaging Style Packaging Code

	•	rapo a ricor	
C	apacitance Tole	rance	
	Tolerance Code	Tolerance	
	K	±15%	
	M	+ 20%	

Tane & Reel

Nominal Capacitance (pF)

The capacitance is expressed in three digit codes and in units of pico Farads (pF). The first and second digits identify the first and second significant figures of the capacitance. The third digit identifies the multiplier. R designates a decimal point.

Capacitance Code	Capacitance
0R5	0.5pF
010	1pF
102	1,000pF (1nF)
105	1,000,000pF (1µF)





C0510 [EIA CC0204]

Capacitance Range Chart

Temperature Characteristics: X6S (± 22%)

Rated Voltage: 4V (0G)

riatou voltago. Iv (ou)							
Capacitance	Cap		X6S				
(pF)	Code	Tolerance	0G				
(pr)	Code		(4V)				
10,000	103	M: ± 20%					
22,000	223						
47,000	473						
100,000	104						
220,000	224						
470,000	474						
1,000,000	105						
2,200,000	225						

Standard Thickness
0.30 mm



C0510 [EIA CC0204]

Class 2 (Temperature Stable)

Temperature Characteristics X6S (-55 to +105°C, ±22%)

TDK Part Number (Ordering Code)	Temperature Characteristics	Rated Voltage	Capacitance (pF)	Capacitance Tolerance	Thickness (mm)
C0510X6S0G104M	X6S	4V	100,000	± 20%	0.30 ± 0.05
C0510X6S0G224M	X6S	4V	220,000	± 20%	0.30 ± 0.05
C0510X6S0G474M	X6S	4V	470,000	± 20%	0.30 ± 0.05





C0816 [EIA CC0306]

Capacitance Range Chart

Temperature Characteristics: X7R, (± 15%), X7S (± 22%), X5R (± 15%), X6S (± 22%)

Rated Voltage: 16V (1C), 10V (1A), 6.3V (0J), 4V (0G)

Consoltones			X7R		X7S X5F		5R	X6S
Capacitance (pF)	Cap Code	Tolerance	1C (16V)	0J (6.3V)	0G (4V)	1A (10V)	0J (6.3V)	0G (4V)
10,000	103	K: ± 10%						
22,000	223	M: ± 20%						
47,000	473							
100,000	104							
220,000	224							
470,000	474							
1,000,000	105							
2,200,000	225							

Standard Thickness
0.50 mm



C0816 [EIA CC0306]

Class 2 (Temperature Stable)

Temperature Characteristics X7R (-55 to +125°C, ±15%), X7S (-55 to +125°C, ±2%), X5R (-55 to +85°C, ±15%)

TDK Part Number (Ordering Code)	Temperature Characteristics	Rated Voltage	Capacitance (pF)	Capacitance Tolerance	Thickness (mm)
C0816X7R1C103K	X7R	16V	10,000	± 10%	0.50 ± 0.10
C0816X7R1C223K	X7R	16V	22,000	± 10%	0.50 ± 0.10
C0816X7R1C473K	X7R	16V	47,000	± 10%	0.50 ± 0.10
C0816X7R1C104K	X7R	16V	100,000	± 10%	0.50 ± 0.10
C0816X7R0J224K	X7R	6.3V	220,000	± 10%	0.50 ± 0.10
C0816X7S0G474K	X7S	4V	470,000	± 10%	0.50 ± 0.10
C0816X7S0G105M	X7S	4V	1,000,000	± 20%	0.50 ± 0.10
C0816X7S0G225M	X7S	4V	2,200,000	± 20%	0.50 ± 0.10
C0816X5R1A224K	X5R	10V	220,000	± 10%	0.50 ± 0.10
C0816X5R1A474K	X5R	10V	470,000	± 10%	0.50 ± 0.10
C0816X5R0J474K	X5R	6.3V	470,000	± 10%	0.50 ± 0.10
C0816X5R0J105M	X5R	6.3V	1,000,000	± 20%	0.50 ± 0.10
C0816X5R0J225M	X5R	6.3V	2,200,000	± 20%	0.50 ± 0.10





C1220 [EIA CC0508]

Capacitance Range Chart

Temperature Characteristics: X7R, (± 15%), X5R (± 15%) Rated Voltage: 50V (1H), 25V (1E), 16V (1C), 10V (1A), 6.3V (0J)

Consoitones	Con		X7R				X5R
Capacitance (pF)	Cap Code	Tolerance	1H (50V)	1E (25V)	1C (16V)	0J (6.3V)	1A (10V)
10,000	103	K: ± 10%					
22,000	223	M: ± 20%					
47,000	473						
100,000	104						
220,000	224						
470,000	474						
1,000,000	105						

Standard Thickness
0.85 mm



C1220 [EIA CC0508]

Class 2 (Temperature Stable)

Temperature Characteristics X7R (-55 to +125°C, ±15%), X5R (-55 to +85°C, ±15%)

TDK Part Number (Ordering Code)	Temperature Characteristics	Rated Voltage	Capacitance (pF)	Capacitance Tolerance	Thickness (mm)
C1220X7R1H103K	X7R	50V	10,000	± 10%	0.85 ± 0.10
C1220X7R1H223K	X7R	50V	22,000	± 10%	0.85 ± 0.10
C1220X7R1H473K	X7R	50V	47,000	± 10%	0.85 ± 0.10
C1220X7R1E104K	X7R	25V	100,000	± 10%	0.85 ± 0.10
C1220X7R1C224K	X7R	16V	220,000	± 10%	0.85 ± 0.10
C1220X7R0J474K	X7R	6.3V	470,000	± 10%	0.85 ± 0.10
C1220X7R0J105M	X7R	6.3V	1,000,000	± 20%	0.85 ± 0.10
C1220X5R1A474K	X5R	10V	470,000	± 10%	0.85 ± 0.10
C1220X5R1A105M	X5R	10V	1,000,000	± 20%	0.85 ± 0.10





C1632 [EIA CC0612]

Capacitance Range Chart

Temperature Characteristics: X7R, (± 15%), X7S (± 22%), X5R (± 15%) Rated Voltage: 50V (1H), 25V (1E), 16V (1C), 10V (1A), 6.3 (0J), 4V (0G)

Capacitance (pF)	Con			X.	7R		X7S	X	5R
	Cap Code	Loierance	1H (50V)	1E (25V)	1C (16V)	0J (6.3V)	0G (4V)	1A (10V)	0J (6.3V)
10,000	103	K: ± 10%							
22,000	223	M: ± 20%							
47,000	473								
100,000	104								
220,000	224								
470,000	474								
1,000,000	105								
2,200,000	225]							
4,700,000	475]							
10,000,000	106								

Standard Thickness

0.70 mm 1.30 mm





C1632 [EIA CC0612]

Class 2 (Temperature Stable)

Temperature Characteristics X7R (-55 to +125°C, ±15%), X7S (-55 to +125°C, ±2%), X5R (-55 to +85°C, ±15%)

TDK Part Number (Ordering Code)	Temperature Characteristics	Rated Voltage	Capacitance (pF)	Capacitance Tolerance	Thickness (mm)
C1632X7R1H103K	X7R	50V	10,000	± 10%	0.70 ± 0.10
C1632X7R1H223K	X7R	50V	22,000	± 10%	0.70 ± 0.10
C1632X7R1H473K	X7R	50V	47,000	± 10%	0.70 ± 0.10
C1632X7R1H104K	X7R	50V	100,000	± 10%	0.70 ± 0.10
C1632X7R1H224K	X7R	50V	220,000	± 10%	1.15 ± 0.10
C1632X7R1E224K	X7R	25V	220,000	± 10%	0.70 ± 0.10
C1632X7R1E474K	X7R	25V	470,000	± 10%	1.15 ± 0.10
C1632X7R1C474K	X7R	16V	470,000	± 10%	0.70 ± 0.10
C1632X7R1C105K	X7R	16V	1,000,000	± 10%	1.15 ± 0.10
C1632X7R0J105M	X7R	6.3V	1,000,000	± 20%	0.70 ± 0.10
C1632X7R0J225M	X7R	6.3V	2,200,000	± 20%	1.15 ± 0.10
C1632X7S0G475M	X7S	4V	4,700,000	± 20%	1.30 ± 0.10
C1632X7S0G106M	X7S	4V	10,000,000	± 20%	1.30 ± 0.10
C1632X5R1A105M	X5R	10V	1,000,000	± 20%	0.70 ± 0.10
C1632X5R1A225M	X5R	10V	2,200,000	± 20%	1.15 ± 0.10
C1632X5R0J475M	X5R	6.3V	4,700,000	± 20%	1.30 ± 0.10
C1632X5R0J106M	X5R	6.3V	10,000,000	± 20%	1.30 ± 0.10



No.	Item	Performance			Test or	r Insp	ection Meth	od		
1	External Appearance	No defects which may affect performance.				Inspect	with m	nagnifying glas	ss (3×).	
2	Insulation Resistance	10,000M Ω or 500M Ω •μF min. (whichever smaller). As for the capacitor of rated voltage 16, 10, 6.3 and 4V DC, 100M Ω •μF min.			Apply ra	ated vo	oltage for 60s.			
3	Voltage Proof		and test volt ion breakdo		thout other damage.			ted voltage for narge current s	1 ~ 5s. shall not exceed	50mA.
4	Capacitance	Within	Within the specified tolerance.			Meas Frequ	_	Rated Voltage	Measuring Voltage	
								50V ~ 6.3V	1.0±0.2 V _{rms}	
					1kHz±10%	4V	0.5 - 5 V _{rms}			
							4			
5	Dissipation Factor	T.C.	Rated Volta		D.F.	See No.	.4 in th	is table for me	easuring condition	on.
	(Class 2)	X7R	50V, 25V D		0.03 max.	=				
	(Class 2)	X7R X5R	16V, 10V, 6 DC	6.3V	0.05 max.					
		X7S X6S X5S	4V DC		0.12 max.					
6	Temperature Characteristics	=	itance Chan		1				red by the step	
	of Capacitance			C Perce	ent	for each	step.			
	(Class 2)	X5	5R			∆C be c	alcula	ted ref. STEP3	3 reading	
		X7	'R	±15%		Step	Tem	perature (°C)		
		X5				1		rence temp. \pm 2		
		Xe	I	±22%		2		operating temp.		
		X7	7S			3		rence temp. ± 2		
						4	Max.	operating temp	. ± 2	
7	Robustness of Terminations		n of termina		ming off, other abnormal		ix 1) a	nd apply a pus	on P.C. board (shing force of 5	
							F		- 5N (2N for C0)	510)



No.	Item	Performance		Test or Inspection Method		
8	Bending	No mechanical da	mage.	Reflow solder the capacitor on P.C. board (shown in Appendix 2) and bend it for 1mm.		
				50 F R230 Unit: mm		
9	Solderability	New solder to cove termination.	er over 75% of	Completely soak both terminations in solder at 235 \pm 5°C for 2 \pm 0.5s.		
		25% may have pin but not concentrate	holes or rough spots ed in one spot.	Solder: H63A (JIS Z 3282)		
		Ceramic surface or not be exposed du shifting of terminat		Flux: Isopropyl alcohol (JIS K 8839) Rosin (JIS K 5902) 25% solid solution.		
			A section			
10	Resistance to sol	der heat		Completely soak both terminations in solder at 260 ±		
	External appearance		wed and terminations t least 60% with new	5°C for 5 ± 1s. Preheating condition Temp.: 150 ± 10°C		
	Capacitance	Characteristics	Change from the value before test	Time: 1 ~ 2min. Flux:		
		Class 2 X7R X7S X5R X6S	± 7.5 %	Isopropyl alcohol (JIS K 8839) Rosin (JIS K 5902) 25% solid solution. Solder: H63A (JIS Z 3282)		
	D.F. (Class 2)	Meet the initial spec.		Leave the capacitor in ambient conditions for 24 \pm 2h		
	Insulation Resistance Voltage proof No insulation breakdown or other damage.		ec.	before measurement.		





No.	Item	Performa	ance		Test or	Inspection Method		
11	Vibration External No mechanical damage.			mage.	Solder the capacitors on P.C. board (shown in Appendix 1) before testing.			
	appearance	rio moona			Vibrate the capacitor with amplitude of 1.5mm P-l changing the frequencies from 10Hz to 55Hz and			
	Capacitance	Characteri	istics	Change from the value before test	to 10Hz	in about 1min.		
		Class 2	X7R X7S X5R X6S	± 7.5 %	Repeat this for 2h each in 3 perpendicular directions.			
	D.F. (Class 2)	Meet the ir	nitial spe	ec.	_			
12	Temperature cycle	e				ne capacitors on P.C. board	I (shown in	
	External appearance	No mecha	nical da	mage.	Expose	x 1) before testing. the capacitor in the conditions at 5 times consecutively.	ons step1 through 4	
	Capacitance	Characteri		Change from the value before test	Leave th	ne capacitor in ambient con- neasurement.	ditions for 24 \pm 2h	
			X7R X7S		Step	1	Time (min.)	
		Class 2	X5R	± 7.5 %	1 3tep	Temperature (°C) Min. operating temp. ±3	30 ± 3	
			X6S		_ 2	Reference Temp.	2-5	
_	D. F. (OL O)	Marithan	. 101 - 1		<u> </u>	Max. operating temp. \pm 2	30 ± 2	
	D.F. (Class 2)	Meet the ir	nitiai spe	€C.	_ 4	Reference Temp.	2 - 5	
	Insulation Resistance	1,000M Ω c smaller.	or 50MΩ	•μF min. whichever				
	Voltage Proof	No insulati damage.	ion brea	kdown or other				
13	Moisture Resistan	nce (Steady	State)			ne capacitor on P.C. board	(shown in	
	External appearance	No mecha	nical da	mage.	Leave a	x 1) before testing. t temperature 40 \pm 2°C, 90	to 95%RH for 500	
	Capacitance	Characteri	istics	Change from the value before test		ne capacitor in ambient conc neasurement.	ditions for 24 \pm 2h	
		Class 2	X7R X7S X5R X6S	± 12.5 %		icasurenient.		
	D.F. (Class 2)	X7S: 200° X5R: 200°	% of initi % of initi % of initi	ial spec. max. al spec. max. ial spec. max. al spec. max.	_			
	Insulation Resistance	X6S: 200% of initial spec. max. 1,000MΩ or $50M\Omega^{\bullet}\mu\text{F}$ min. (whichever smaller). As for the capacitor of rated voltage 16, 10, 6.3 and 4V DC, $10M\Omega^{\bullet}\mu\text{F}$ min.						





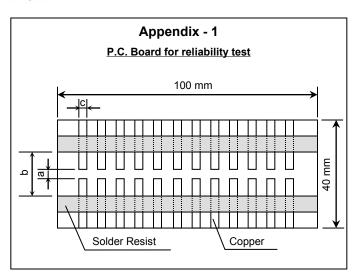
No.	Item	Performa	nce		Test or Inspection Method
14	Moisture ResistanceExternal No mechanical da appearance		nical daı	mage.	Solder the capacitors on P.C. board (shown in Appendix 1) before testing. Apply the rated voltage at temperature 40 \pm 2°C and
	D.F. (Class 2) Insulation Resistance	The contract of the contract		± 12.5 % al spec. max.	 90 to 95%RH for 500 +24, 0h. Charge/discharge current shall not exceed 50mA. Leave the capacitor in ambient conditions for 48 ± 4h before measurement. Voltage conditioning: Voltage treats the capacitor under testing temperature and voltage for 1hour. Leave the capacitor in ambient conditions for 24 ± 2h before measurement. Use this measurement for initial value.
15	Life External appearance	min. No mechar			Reflow Solder the capacitor on P.C. board (shown in Appendix 1) before testing. Apply rated voltage at maximum operating temperature
	Capacitance	Characteris Class 2	X7R X7S X5R X6S	Change from the value before test	 ± 2°C for 1,000 +48, 0h. Charge/discharge current shall not exceed 50mA. Leave the capacitor in ambient conditions for 24 ± 2h before measurement. Voltage conditioning:
	D.F. (Class 2)	X7S: 200% X5R: 200%	of initia of initia of initia	al spec. max. al spec. max. al spec. max. al spec. max.	Voltage treats the capacitor under testing temperature and voltage for 1hour. Leave the capacitor in ambient conditions for 48 ± 4h before measurement. Use this measurement for initial value.
	Insulation Resistance	1,000MΩ or 50MΩ•μF min. whichever smaller. As for the capacitor of rated voltage 16, 10, 6.3 and 4V DC, 10MΩ•μF min.			

^{*}As for the initial measurement of capacitors on number 6, 10, 11, 12 and 13, leave capacitor at 150 -10, 0° C for 1h and measure the value after leaving capacitor for 24 ± 2h in ambient condition.





C Series – Low ESL Flip Type



Appendix - 2

P.C. Board for bending test

100 mm

b

a

Copper

Material: Glass Epoxy (As per JIS C6484 GE4)

P.C. Board thickness: Appendix 1,2

1.6mm

Copper (thickness 0.035mm)

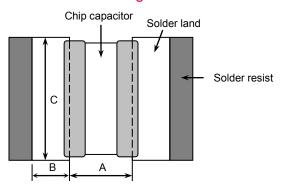
Solder resist

Case	Code	Di	mensions (m	m)
JIS	EIA	а	b	С
C0510	CC0204	0.2	0.6	1.0
C0816	CC0306	0.3	1.0	1.6
C1220	CC0508	0.5	1.6	2.0
C1632	CC0612	0.75	2.2	3.2



C Series – Low ESL Flip Type

Recommended Soldering Land Pattern



Reflow Soldering

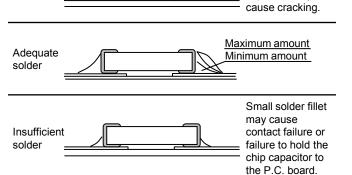
Excessive solder

iteneti Genae	g			Offic. Hilli
Туре	C0510	C0816	C1220	C1632
Symbol	[CC0204]	[CC0306]	[CC0508]	[CC0612]
Α	0.20	0.30	0.50	0.75
В	0.20	0.35	0.55	0.725
С	1.00	1.60	2.00	3.20

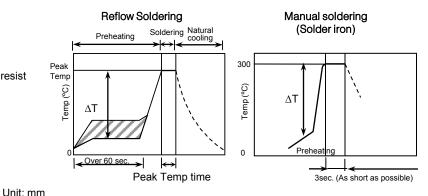
Higher tensile force on the chip

capacitor may

• Recommended Solder Amount



• Recommended Soldering Profile



Recommended soldering duration

Temp./	Reflow S	Soldering
Dura. Solder	Peak temp (°C)	Duration (sec.)
Sn-Pb Solder	230 max.	20 max.
Lead-Free Solder	260 max.	10 max.

Recommended solder compositions Sn-37Pb (Sn-Pb solder) Sn-3.0Ag-0.5Cu (Lead Free Solder)

Preheating Condition

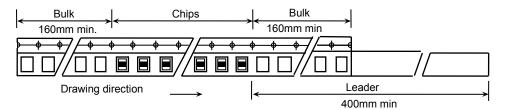
-	
Soldering	Temp. (°C)
Reflow soldering	ΔT ≤ 150
Manual soldering	ΔT ≤ 150



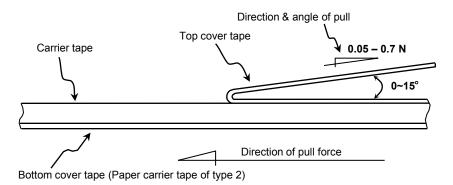


C Series – Low ESL Flip Type

Carrier Tape Configuration

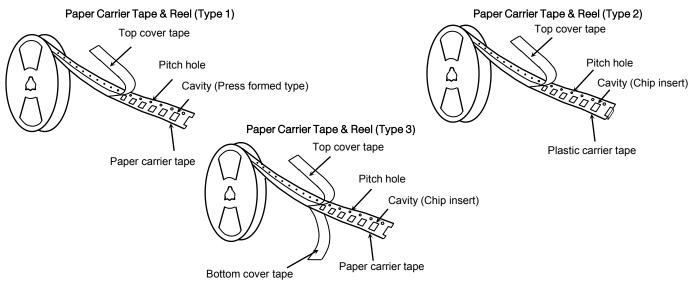


Peel Back Force (Top Tape)



- Carrier tape shall be flexible enough to be wound around a minimum radius of 30mm with components in tape.
- The missing of components shall be less than 0.1%
- · Components shall not stick to the cover tape.
- The cover tape shall not protrude beyond the edges of the carrier tape not shall cover the sprocket holes.

Chip Quantity Per Reel and Structure of Reel (Paper & Plastic)



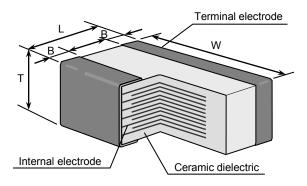
Case	e Code Chip Taping Material		Chip quantity (pcs.)			
JIS	EIA	Thickness	raping material	φ178mm (7") reel	φ330mm (13") reel	
C0510	CC0204	0.50 mm	Paper (Type 1)	15,000	50,000	
C0816	CC0306	0.80 mm	Plastic (Type 3)	4,000	10,000	
C1220	CC0508	0.85 mm	Paper (Type 2)	4,000	10,000	
		0.70 mm		4,000		
C1632	CC0612	1.15 mm Plastic (Type 3)	2.000	10,000		
		1.30 mm		2,000		





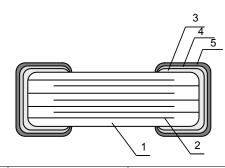
C Series – Low ESL Flip Type

Shape & Dimensions



Case Code		Dimensions (mm)				
JIS	EIA	L	W	Т	В	G
C0510	CC0204	0.52	1.00	0.50	0.10 min.	0.09 min.
C0816	CC0306	0.80	1.60	0.80	0.10 min.	-
C1220	CC0508	1.25	2.00	0.85	0.20 min.	0.40 min.
				0.70		
C1632	CC0612	1.60	3.20	1.15	0.20 min.	0.50 min.
				1.30		

Inside Structure & Material System



No.	NAME	MATERIAL		
		Class 2		
(1)	Ceramic Dielectric	BaTiO ₃		
(2)	Internal Electrode	Nickel (Ni)		
(3)		Copper (Cu)		
(4)	Termination	Nickel (Ni)		
(5)		Tin (Sn)		

Environmental Information

TDK Corporation established internal product environmental assurance standards that include the six hazardous substances banned by the EU RoHS Directive¹ enforced on July 1, 2006 along with additional substances independently banned by TDK and has successfully completed making general purpose electronic components conform to the RoHS Directive².

- 1. Abbreviation for Restriction on Hazardous Substances, which refers to the regulation EU Directive 2002/95/EC on hazardous substances by the European Union (EU) effective from July 1, 2006. The Directive bans the use of six specific hazardous substances in electric and electronic devices and products handled within the EU. The six substances are lead, mercury, cadmium, hexavalent chromium, PBB (polybrominated biphenyls), and PBDE (polybrominated diphenyl ethers).
- This means that, in conformity with the EU Directive 2002/95/EC, lead, cadmium, mercury, hexavalent chromium, and specific bromine-based flame retardants, PBB and PBDE, have not been used, except for exempted applications.
- For REACH (SVHC: 15 substances according to ECHA / October 2008): All TDK MLCC do not contain these 15 substances.
- For European Directive 2000/53/CE and 2005/673/CE:
 Cadmium, Hexavalent Chromium, Mercury, Lead are not contained in all TDK MLCC.
- For European Directive 2003/11/CE: Pentabromodiphenylether, Octabromodiphenylether are not contained in all TDK MLCC.